

09-06-2000

FORM PTO-1596
1-31-92

RECC

U.S. DEPARTMENT OF COMMERCE
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DOCKET NO.: 4423-040

101450666

PATENTS ONLY

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereto:

1. Name of conveying party(ies):

Yu-Hsin LIU

Additional name(s) of conveying party(ies) attached?

2. Name and address of receiving party(ies):

Name: Powerchip Semiconductor Corporation

Internal Address:

Street Address:

No. 12, Li Hsiang Rd. I. Science-Based Industrial Park

City: Hsinchu

State or Area:

Zip/Postal Code:

Country: TAIWAN R.O.C.

Additional name(s) & address(es) attached?

3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other

Execution Date: August 8, 2000

4. Application number(s) or patent number(s):

09640184

If the document is being filed together with a new application, the execution date of the application is: August 8, 2000

A. Patent Application No(s).

B. Patent No(s).

Additional numbers attached?

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: LOWE HAUPTMAN GOPSTEIN GILMAN & BERNER

Internal Address:

Street Address: 1700 Diagonal Road, Suite 310

City: Alexandria

State: VA

ZIP: 22314

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41)

\$40.00

Is enclosed

8. Deposit account number: 07-1337

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9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*Benjamin J. Hauptman
Registration No. 29,310

Signature

August 17, 2000

Date

Total number of pages comprising cover sheet: 1

CMB No. 0851-0011 (exp. 4/94)

Jc875 U.S. PTO
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08/28/2000 MPEPLES 00000010 09640184
02 FC:581

48.00 OP

PATENT
REEL: 011034 FRAME: 0776

ASSIGNMENT OF PATENT APPLICATION

Q0679

For good and valuable consideration, receipt of which hereby acknowledged,

I/We,

(a) Yu-Hsin Liu

residing at

(a) No 12, Li Hsing Rd I. Science -Based Industrial Park, Hsinchu, Taiwan, R.O.C.

assign and transfer to: Powerchip Semiconductor Corp

a corporation organized under the law of Taiwan and having a place of business at :

No. 12, Li Hsing Rd I. Science -Based Industrial Park, Hsinchu, Tawian, R.O.C.

its successors and assigns, my entire right, title and interest, including the right of priority, in, to and under an application for Letters Patent of the United States entitled:

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including divisions, reissues, continuations and extensions thereof, and all rights of priority without further authorization from me; I agree to execute all papers useful in connection with said United States application, and generally to do everything possible to aid said assignee, its successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in United States; and I request the Commissioner of Patents and Trademarks to issue all patents granted for said invention to the above-named assignee, its successors and assigns.

Joint Inventor (a)	Yu-Hsin Liu		
Inventor' s Signature	Yu-Hsin Liu	Date	2000/8/8
Residence	Hsinchu	Citizenship	Taiwan, R.O.C.